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ATTORNEY DOCKET NO. 43890-485
PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	
Hiroshi HAJI, et al.	Group Art Unit: 2823
Serial No.: 09/781,563	Examiner: GEORGE R. FOURSON
Filed: February 13, 2001	
For: METHOD OF MANUFACTURING) SEMICONDUCTOR DEVICE )	TECHA

## **ELECTION UNDER 35 U.S.C. § 121**

Hon. Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the restriction requirement set forth in the Office Action mailed October 2, 2002, having a shortened statutory period for response set to expire November 2, 2002, wherein the Examiner required restriction between the following Species:

Species I - wherein the first cutting is through the resin layer;

Species II - wherein the first cutting is through the wafer;

Species III - wherein the first cutting is forming grooves on the surface of

the wafer wherein devices are formed; and

Species IV - wherein the backside of the wafer is ground followed by

forming grooves on the ground surface.

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Applicants elect without traverse Species II, with claims 1-7 readable thereon for initial prosecution on the merits.

Applicants believe that no extension of time is required. However, this conditional petition is being made to provide for the possibility that Applicants have inadvertently overlooked the need for a petition for extension of time. The Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment to Deposit Account No. 50-0417.

Respectfully submitted,

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